RELIABILITY REPORT

FOR

MAX4678EUE+

PLASTIC ENCAPSULATED DEVICES

September 30, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX4678EUE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX4677/MAX4678/MAX4679 quad analog switches feature 1.6 max on-resistance (RON) when operating from a dual ±5V supply. RON is matched between channels to 0.3 max and is flat (0.4 max) over the specified signal range. Each switch can handle Rail-to-Rail analog signals. Off-leakage current is 0.1nA at +25°C. These switches are ideal in low-distortion applications and are the preferred solution over mechanical relays in automated test equipment. They have low power requirements, require less board space, and are more reliable than mechanical relays. The MAX4677 has four normally closed (NC) switches, and the MAX4678 has four normally open (NO) switches. The MAX4679 has two NC and two NO switches and features guaranteed break-before-make switching. The MAX4677/MAX4678/MAX4679 operate from either a single +2.7V to +11V or dual ±2.7V to ±5.5V supplies, making them ideal for use in digital card applications and single-ended 75 systems. These devices feature a separate logic supply input that operates from +2.7V to V+, allowing independent logic and analog supplies.

II. Manufacturing Information

A. Description/Function:	2 , Quad, SPST, CMOS Analog Switches
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	April 22, 2000

III. Packaging Information

A. Package Type:	16-pin TSSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0177
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	106°C/W
K. Single Layer Theta Jc:	27°C/W
L. Multi Layer Theta Ja:	90°C/W
M. Multi Layer Theta Jc:	27°C/W

IV. Die Information

A. Dimensions:	104 X 144 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 231 \times 2} \quad \text{(Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 4.8 \times 10^{-9}$

λ = 4.8 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.04 @ 25C and 0.69 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot N7YBB3002D, D/C 0144)

The AH47-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-200mA.

Table 1
Reliability Evaluation Test Results

MAX4678EUE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	71 80 80	0 0 0	I7YCAQ001D, DC 0010 N7YAB3003B, DC 0230 I7YAAQ001C, DC 0010

Note 1: Life Test Data may represent plastic DIP qualification lots.